

ABSTRACT OF DISCLOSURE

The method of mounting an electronic part is capable of securely mounting the electronic part having fine solder bumps without excessively heating the part. The method of comprises the steps of: applying flux-fill, which acts as flux and under-filling resin, on a surface of a mount board, in which electrodes are formed; respectively connecting solder bumps of the electronic part with the electrodes; and simultaneously filling a gap between the electronic part and the mount board with the flux-fill, wherein the solder bumps are made contact with the electrodes, and ultrasonic vibration energy is applied to contact portions of the solder bumps and the electrodes in the connecting step.